Forward-Looking Statements

This document may contain forward-looking statements regarding the business, results of operations, financial condition and earnings outlook of AIXTRON within the meaning of the safe harbor provisions of the US Private Securities Litigation Reform Act of 1995. These statements may be identified by words such as “may”, “will”, “expect”, “anticipate”, “contemplate”, “intend”, “plan”, “believe”, “continue” and “estimate” and variations of such words or similar expressions. These forward-looking statements are based on our current views and assumptions and are subject to risks and uncertainties. You should not place undue reliance on these forward-looking statements. Actual results and trends may differ materially from those reflected in our forward-looking statements. This could result from a variety of factors, such as actual customer orders received by AIXTRON, the level of demand for deposition technology in the market, the timing of final acceptance of products by customers, the condition of financial markets and access to financing for AIXTRON, general conditions in the market for deposition plants and macroeconomic conditions, cancellations, rescheduling or delays in product shipments, production capacity constraints, extended sales and qualification cycles, difficulties in the production process, the general development in the semi-conductor industry, increased competition, fluctuations in exchange rates, availability of public funding, fluctuations and/or changes in interest rates, delays in developing and marketing new products, a deterioration of the general economic situation and any other factors discussed in any reports or other announcements field by AIXTRON with the U.S. Securities and Exchange Commission. Any forward-looking statements contained in this document are based on current expectations and projections of the Executive Board and on information currently available to it and are made as at the date hereof. AIXTRON undertakes no obligation to revise or update any forward-looking statements as a result of new information, future events or otherwise, unless expressly required to do so by law.

Due to rounding, numbers presented throughout this presentation may not add up precisely to the totals indicated and percentages may not precisely reflect the absolute figures for the same reason.

Our registered trademarks: AIXACT®, AIXTRON®, Atomic Level SolutionS®, Close Coupled Showerhead®, CRIUS®, Gas Foil Rotation®, OVPD®, Planetary Reactor®, PVPD®, TriJet®, Optacap™
Who we are

- Headquarters based in Herzogenrath, Germany
- Worldwide presence with 12 sales/representatives offices and production facilities
- Company founded in 1983 – over 30 years of experience
- ~730 employees
- Technology leader in deposition systems
- More than 3,000 deposition systems delivered all over the world
- State of the art R&D center and demo facilities
- Annual R&D budget of approx. € 60 Million
Our Vision


Technology.
We are the recognized technology leader in complex material deposition.

Materials.
We enable our customers to successfully shape the markets of the future, exploiting the potential offered by new materials.

Performance.
We deliver the performance driving economic success through our expertise, our employees and the quality of our products.
Our Technology. Your FUTURE.

AIXTRON TECHNOLOGIES

Compound Semiconductors

Silicon Semiconductors

Organic

Carbon

LED Lighting

Memory & Logic

OLED

Power Management
## Our Technology Portfolio

### Compound Semiconductors
- **MOCVD**
  - **LEDs, Lasers and Optoelectronics**
    - LEDs for display: TVs, mobile phones, tablets, etc.
    - LEDs for lighting
    - LEDs for automotive
    - LEDs for datacom
    - Lasers for telecom, consumer electronics
    - Photovoltaics

### Silicon Semiconductors
- **ALD/MOCVD**
  - **Power Management**
    - GaN / SiC
      - RF transistors
      - AC-DC converters
      - DC-DC converters
      - Solar inverters
      - Motor drives in industrial applications automotive and consumer electronics

### Organic
- **OVPD®/PVPD®/TFE**
  - **Silicon Semiconductors**
    - DRAM Dielectric and Metal Electrode
    - Flash Inter Poly Dielectric and Metals
    - ReRAM and PCRAM Active element and Electrode
    - Logic Gate stack
    - Logic High Mobility Channel

### Carbon
- **PECVD**
  - **Organic Electronics**
    - OLEDs for display: TVs, mobile phones, tablets, etc.
    - Thin Film Encapsulation
    - OLEDs for lighting
    - Organic, flexible electronics
    - Organic Photovoltaics

### Graphene, CNTs and CNWs
- **Increasing Equipment Demand**
  - Transistors
  - Interconnects
  - Flexible Electronics
  - Energy Storage
  - Sensors, etc.

### Equipment Demand
- **Equipment Demand Expected by:**
  - 2016/2017
  - 2018 and beyond
  - 2015 and beyond
  - 2015 and beyond
  - 2015 and beyond
Revenue Analysis

Q1/2016:
by equipment & spares

Q1/2016:
by end application
(equipment only)

Q1/2016:
by region

- Equipment
- Spares

- LED
- Silicon
- Power Electronics
- Optoelectronics
- Others

- Asia
- Europe
- USA
- Others
USD order intake and backlog were recorded at the prevailing budget rate (2016: $1.10/€)
USD revenues were converted at the actual period average FX rate (Q1/2015: $1.09/€)
## Consolidated Income Statement*

<table>
<thead>
<tr>
<th>(€ million)</th>
<th>Q1/16</th>
<th>Q1/15</th>
<th>+/-</th>
<th>Q1/16</th>
<th>Q4/15</th>
<th>+/-</th>
</tr>
</thead>
<tbody>
<tr>
<td>Revenues</td>
<td>21.4</td>
<td>40.3</td>
<td>-47%</td>
<td>21.4</td>
<td>62.5</td>
<td>-66%</td>
</tr>
<tr>
<td>Cost of sales</td>
<td>18.3</td>
<td>31.5</td>
<td>-42%</td>
<td>18.3</td>
<td>42.8</td>
<td>-57%</td>
</tr>
<tr>
<td>Gross profit</td>
<td>3.1</td>
<td>8.8</td>
<td>-65%</td>
<td>3.1</td>
<td>19.6</td>
<td>-84%</td>
</tr>
<tr>
<td><strong>Gross Margin</strong></td>
<td><strong>15%</strong></td>
<td><strong>22%</strong></td>
<td><strong>-7 pp</strong></td>
<td><strong>15%</strong></td>
<td><strong>31%</strong></td>
<td><strong>-16 pp</strong></td>
</tr>
<tr>
<td>Selling expenses</td>
<td>2.9</td>
<td>3.3</td>
<td>-12%</td>
<td>2.9</td>
<td>2.6</td>
<td>12%</td>
</tr>
<tr>
<td>General &amp; admin expenses</td>
<td>3.8</td>
<td>4.3</td>
<td>-12%</td>
<td>3.8</td>
<td>4.2</td>
<td>-10%</td>
</tr>
<tr>
<td>R&amp;D</td>
<td>13.3</td>
<td>12.9</td>
<td>3%</td>
<td>13.3</td>
<td>14.4</td>
<td>-8%</td>
</tr>
<tr>
<td>Net other op.(income)/expenses</td>
<td>-2.2</td>
<td>-3.0</td>
<td>27%</td>
<td>-2.2</td>
<td>0.0</td>
<td>n.m.</td>
</tr>
<tr>
<td>EBITDA</td>
<td>-11.7</td>
<td>-6.4</td>
<td>-83%</td>
<td>-11.7</td>
<td>1.3</td>
<td>n.m.</td>
</tr>
<tr>
<td>EBIT</td>
<td>-14.7</td>
<td>-8.8</td>
<td>-67%</td>
<td>-14.7</td>
<td>-1.5</td>
<td>n.m.</td>
</tr>
<tr>
<td><strong>EBIT Margin</strong></td>
<td><strong>-69%</strong></td>
<td><strong>-22%</strong></td>
<td><strong>-47 pp</strong></td>
<td><strong>-69%</strong></td>
<td><strong>-2%</strong></td>
<td><strong>-67 pp</strong></td>
</tr>
<tr>
<td>Result before tax</td>
<td>-14.6</td>
<td>-8.5</td>
<td>-72%</td>
<td>-14.6</td>
<td>-1.4</td>
<td>n.m.</td>
</tr>
<tr>
<td><strong>Pre-Tax Margin</strong></td>
<td><strong>-68%</strong></td>
<td><strong>-21%</strong></td>
<td><strong>-47 pp</strong></td>
<td><strong>-68%</strong></td>
<td><strong>-2%</strong></td>
<td><strong>-66 pp</strong></td>
</tr>
<tr>
<td>Net result</td>
<td>-15.5</td>
<td>-9.5</td>
<td>-63%</td>
<td>-15.5</td>
<td>-1.9</td>
<td>n.m.</td>
</tr>
<tr>
<td><strong>Net Return on Sales</strong></td>
<td><strong>-72%</strong></td>
<td><strong>-23%</strong></td>
<td><strong>-49 pp</strong></td>
<td><strong>-72%</strong></td>
<td><strong>-3%</strong></td>
<td><strong>-69 pp</strong></td>
</tr>
</tbody>
</table>

*) rounded figures; may not add up
## Consolidated Statement of Financial Position*

<table>
<thead>
<tr>
<th>(€ million)</th>
<th>31/3/16</th>
<th>31/12/15</th>
<th>31/3/15</th>
</tr>
</thead>
<tbody>
<tr>
<td>Property, plant &amp; equipment</td>
<td>79.0</td>
<td>81.3</td>
<td>79.4</td>
</tr>
<tr>
<td>Goodwill</td>
<td>74.6</td>
<td>75.9</td>
<td>65.7</td>
</tr>
<tr>
<td>Other intangible assets</td>
<td>6.0</td>
<td>6.4</td>
<td>2.3</td>
</tr>
<tr>
<td>Others</td>
<td>3.3</td>
<td>3.9</td>
<td>5.0</td>
</tr>
<tr>
<td><strong>Non-current assets</strong></td>
<td><strong>162.9</strong></td>
<td><strong>167.6</strong></td>
<td><strong>152.5</strong></td>
</tr>
<tr>
<td>Inventories, WIP &amp; Finished Goods</td>
<td>73.6</td>
<td>70.8</td>
<td>88.8</td>
</tr>
<tr>
<td>Trade receivables</td>
<td>18.2</td>
<td>26.0</td>
<td>26.2</td>
</tr>
<tr>
<td>Others</td>
<td>9.1</td>
<td>8.2</td>
<td>12.3</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalents incl. CD</td>
<td>181.9</td>
<td>209.4</td>
<td>263.2</td>
</tr>
<tr>
<td><strong>Current Assets</strong></td>
<td><strong>282.8</strong></td>
<td><strong>314.4</strong></td>
<td><strong>390.5</strong></td>
</tr>
<tr>
<td>Shareholders' equity</td>
<td>375.6</td>
<td>396.5</td>
<td>419.2</td>
</tr>
<tr>
<td><strong>Non-current liabilities</strong></td>
<td><strong>3.0</strong></td>
<td><strong>3.6</strong></td>
<td><strong>1.3</strong></td>
</tr>
<tr>
<td>Trade payables</td>
<td>8.8</td>
<td>9.8</td>
<td>12.8</td>
</tr>
<tr>
<td>Advance payments from customers</td>
<td>32.1</td>
<td>24.0</td>
<td>79.6</td>
</tr>
<tr>
<td>Others</td>
<td>26.2</td>
<td>48.0</td>
<td>30.1</td>
</tr>
<tr>
<td><strong>Current liabilities</strong></td>
<td><strong>67.1</strong></td>
<td><strong>81.8</strong></td>
<td><strong>122.4</strong></td>
</tr>
<tr>
<td><strong>Balance Sheet total</strong></td>
<td><strong>445.7</strong></td>
<td><strong>482.0</strong></td>
<td><strong>543.0</strong></td>
</tr>
</tbody>
</table>

*) rounded figures; may not add up
## Consolidated Statement of Cash Flows*

<table>
<thead>
<tr>
<th>(€ million)</th>
<th>Q1/16</th>
<th>Q1/15</th>
<th>Q1/16</th>
<th>Q4/15</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash Flow from operating activities</td>
<td>-19.4</td>
<td>-10.1</td>
<td>-19.4</td>
<td>-32.1</td>
</tr>
<tr>
<td>Cash Flow from investing activities</td>
<td>7.1</td>
<td>11.3</td>
<td>7.1</td>
<td>30.1</td>
</tr>
<tr>
<td>Cash Flow from financing activities</td>
<td>0.0</td>
<td>0.0</td>
<td>0.0</td>
<td>0.0</td>
</tr>
<tr>
<td>Exchange rate changes</td>
<td>-2.7</td>
<td>6.2</td>
<td>-2.7</td>
<td>0.8</td>
</tr>
<tr>
<td>Net change in Cash &amp; Cash Equivalents</td>
<td>-15.0</td>
<td>7.4</td>
<td>-15.0</td>
<td>-1.2</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalents (beginning of period)</td>
<td>116.3</td>
<td>116.6</td>
<td>116.3</td>
<td>117.5</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalents (end of period)</td>
<td>101.3</td>
<td>124.0</td>
<td>101.3</td>
<td>116.3</td>
</tr>
<tr>
<td>Change in Cash deposits</td>
<td>-12.2</td>
<td>-14.8</td>
<td>-12.2</td>
<td>-33.0</td>
</tr>
<tr>
<td>Free Cash Flow**</td>
<td>-20.3</td>
<td>-12.1</td>
<td>-20.3</td>
<td>-35.0</td>
</tr>
<tr>
<td>Capex</td>
<td>0.9</td>
<td>3.5</td>
<td>0.9</td>
<td>2.9</td>
</tr>
</tbody>
</table>

*) rounded figures; may not add up  
**) Acquisition cost adjusted; Operating CF + Investing CF + Changes in Cash Deposits
Market Prospects

**Short-Term**
- Further increasing adoption of LEDs for Solid State Lighting
- Increased emergence of wide band gap GaN or SiC based devices for energy efficient power management
- Development of next generation NAND and DRAM memory devices
- Further progress in the development of GaN-on-Silicon LEDs and Wafer Level Packaging

**Mid- to Long-Term**
- Development of new wide-band-gap applications such as RF and System-on-Chip with integrated power management
- Progress in the development of large area OLED devices requiring efficient deposition technologies
- Progress in the development of flexible and rigid OLED devices requiring thin-film encapsulation
- Increased development activity for specialized compound solar cell applications, e.g. multi junction, CPV
- Increasing requirements for High-k and interconnects, implying a new approach to production technologies
- Progress in the development of future logic chips applying wide band gap and high electron mobility materials (III-V-on-Silicon)
- Development of applications using Carbon Nanomaterials (Carbon Nanotubes, Carbon Nanowires, Graphene)
- Development of alternative LED applications such as Visual Light Communication technology, (deep) UV
Our technology. YOUR FUTURE.
AIXTRON TECHNOLOGIES AND PRODUCTS

AIXTRON — Key Enabler for Innovative Future

New Complex Materials

Compound Semiconductors
- GaAs/ GaN (Sensors)
- GaN/SiC (RF/Power – Mobile)
- GaAs/InP (Laser - Datacom)
- GaN (LED – LiFi)

Silicon Semiconductors
- III-V (Next-generation Logic – Real-time Processing)
- Innovative materials (Memory - Big Data)

Organic
- Display, Lighting
- Flexible Electronics
- Organic Photovoltaics

Carbon Nano Structures
- Graphene (Energy Storage)
- 2D materials (Smart Sensors, Energy Storage)

Tech Trends

- Big Data
- IoT & Cloud Computing
- Renewable Energy
- Electronic Vehicles
- Energy Storage
LED Lighting Market: Multiple Tipping Points

LED Lighting Cycle

Various Applications

Different Regions

Numerous Players

LED penetration rate - value basis

Overall
Industrial
Office
Outdoor
Hospitality
Shop
Residential
Architectural

Source: AIXTRON, McKinsey 2012
LED Lighting Market Estimates

Globalization and urbanization to drive LED lighting opportunities:
• Emerging countries: need for energy efficient lighting solutions
• Developed countries: SSL driven by expanding renovation market
• Outdoor: Early adoption streetlight replacement market
• Commercial: LED Light Bulb reaching price tipping point

Source: IHS Q1/2016, Strategies Unlimited

Global LED lamp shipments

LED Market Forecast
Technology Position

- **MOCVD for III-V on Silicon**
- **Carbon**
- **OVPD for OLED deposition**
- **Thin-Film Encapsulation for OLED**
- **ALD for Memory — Customer B & C**
- **ALD for Memory — Customer A**
- **MOCVD for Power Management**
- **MOCVD for LEDs, Lasers and Optoelectronics**

**Processes & Stages**

- **R&D**
- **Demo & Qualification**
- **Pilot Production**
- **High Volume Production**
## Compound Semiconductors – MOCVD

<table>
<thead>
<tr>
<th>Two Reactor Technologies — Planetary Reactor® &amp; Close Coupled Showerhead® (CCS)</th>
</tr>
</thead>
<tbody>
<tr>
<td>• Addressing multiple industries</td>
</tr>
<tr>
<td>• Established industry standard &amp; market leading</td>
</tr>
<tr>
<td>• Configurable, extendable common platform</td>
</tr>
<tr>
<td>• Introduced the latest MOCVD technology - AIX R6</td>
</tr>
</tbody>
</table>

**Planetary Reactor®**  
AIX G5+, 5x8  
- Unique Planetary reactor design  
- Horizontal reactor type

**Close Coupled Showerhead®**  
AIX R6, 31x4”  
- Patented CCS Technology  
- Vertical reactor design
## Compound Semiconductors – Wide Band Gap (WBG) Power Electronics

<table>
<thead>
<tr>
<th>Consumer Electronics &amp; IT</th>
<th>Automotive</th>
<th>Energy</th>
<th>Industrial</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Power Management</strong></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>30V</td>
<td>600V</td>
<td>1.2 kV</td>
<td>≥2kV</td>
</tr>
<tr>
<td>• Electronic appliances</td>
<td>• Infotainment</td>
<td>• General automotive electronic</td>
<td>• UPS</td>
</tr>
<tr>
<td>• Computing</td>
<td>• GPS</td>
<td>• HEV/EV</td>
<td>• Industrial machines</td>
</tr>
<tr>
<td>• Wireless charging</td>
<td>• Connected car</td>
<td>• Charging station</td>
<td>• Building</td>
</tr>
<tr>
<td>• Power supplies</td>
<td>• Autonomous driving</td>
<td>• Inverter / motor drives</td>
<td>• Mining, oil, gas power generation</td>
</tr>
<tr>
<td>• PFC</td>
<td>• EMI/EMC</td>
<td>• Converter</td>
<td>• Shipping/Rail</td>
</tr>
<tr>
<td></td>
<td>• Adaptive cruise control</td>
<td>• Radar test applications</td>
<td></td>
</tr>
</tbody>
</table>

### GaN
- Volume segment

### GaN / SiC

### SiC
- Niche segment
Compound Semiconductors – Wide Band Gap (WBG) Power Electronics

WBG GaN and SiC based Power Management Device Shipments

- Reduced Energy Losses
- High Voltage Range
- Improved power quality
- Higher frequencies
- Higher-temperature operation

WBG Power Electronics: Smaller, Faster, and More Efficient

Source: DOE, IHS Q4/2014
Organic Electronics – OVPD® + Encapsulation

OLED manufacturing process

Front-end
Array process equipment

- Cleaning
- ITO deposition
- Coating
- Etching
- Stripping
- Test and repair

Front-end
Cell process equipment

- Organic material deposition
- Encapsulation

Back-end
Module process equipment

- Cleaning
- Glass cutting
- Bonding
- Cathode deposition
- Aging
- Final test

Targeted technology

Source: DisplaySearch, AIXTRON
Focus Activities

Key competency: **Thin-film deposition**
Value creation: **60%**

**Cumulative Capex**

<table>
<thead>
<tr>
<th>Activity</th>
<th>Cumulative Capex</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cleaning</td>
<td>5%</td>
</tr>
<tr>
<td>Deposition</td>
<td>40%</td>
</tr>
<tr>
<td>Cathode deposition</td>
<td>45%</td>
</tr>
<tr>
<td>Encapsulation</td>
<td>55%</td>
</tr>
<tr>
<td>Module preparation</td>
<td>75%</td>
</tr>
<tr>
<td>Automation</td>
<td>100%</td>
</tr>
</tbody>
</table>

Source: IHS; AIXTRON internal estimates
Organic Electronics – OVPD®

**Product Description – OVPD**

- Proprietary carrier-gas enhanced gas phase deposition approach for organic thin films*
- Based on AIXTRON’s core competence of carrier gas enhanced vapour phase deposition
- Free scalability: suitable for all relevant substrate generations
- Manufacturing technology applicable for OLED displays, OLED lighting, organic semiconductors, and organic photovoltaic
- Proprietary STExS™ evaporation source technology: low thermal stress, high rates, continuous operation

“Disruptive deposition technology for cost efficient OLED manufacturing”

**Product Features**

- High deposition rates for high throughput
- Reduced thermal stress for organic materials
- High material utilization efficiency
- Flexible process control

- Simplified scaling due to
  - Close Coupled Showerhead and
  - Decoupled source technology

- Flexible integration solutions batch and inline
- Reduced number of deposition chamber and footprint
- Scalable: Available for substrate sizes up to Gen8.5 (=2.3 x 2.5 m²)

OVPD demonstrator OLAD (Organic Large Area Demonstrator) (optimized for Generation 8.5 substrate sizes)
Organic Electronics – OPTACap™ PECVD

**Product Description – OptaCap™ PECVD**

- Proprietary PECVD technology based on linear plasma sources
- Based on AIXTRON’s core competence of carrier gas enhanced vapour phase deposition
- Free scalability: suitable for all relevant substrate generations
- Manufacturing technology applicable for barrier applications, i.e. thin film encapsulation: highly flexible, low film stress, high transparent, high water and oxygen permeation barrier,

“Disruptive deposition technology for cost efficient deposition of flexible barrier films”

**Product Features**

- High deposition rates for high throughput
- Flexible process control

- Simplified scaling due to
  - Linear PECVD source technology
  - Multiple source configurations

- Scalable: Available for substrate sizes up to Gen3.5, future: up to Gen8.5

- Highly flexible SiNx-based barrier films at high rates
- Low temperature process (<80°) with low film stress
Silicon Semiconductors – Leading Edge Technologies

At the forefront to extend Moore’s Law

- Memory (ALD)
- Logic transistor (MOCVD- III-V)
- Interconnects (Graphene/CNT)

Source: Gartner 2016

- Total fab capacities
- ≤22nm fab capacities
- "More than Moore"
Silicon Semiconductors - ALD

**Product Description – ALD**

- 300mm ALD Technology
- QXP-8300 Mini-batch system
- High throughput: 2 Process Chambers – 8 stations
- Up to 3 vaporizers and one bubbler
- Applications: DRAM, Logic and Flash High k Dielectric
  Metal electrode: ReRAM and PCRAM Active elements
- Proven in HVM with >40% lower CoO and >90% Uptime in DRAM and Flash Fabs

**“Best-in class technology, state of the art deposition system, lowest CoO”**

**Product Features**

- Up to 3 patented TriJet vaporizers
- Small volume confined process space ensure short ALD cycle time
- > 40% less precursor consumption
- Efficient purge
- Isolated multi wafer processing with > 40% higher throughput
- Close Coupled Showerhead for uniform distribution
- Flexibility and ease of maintenance
Carbon Nanomaterials – PECVD

Graphene and Carbon Nanotube Deposition Systems

- Proprietary thermal and plasma enhanced chemical vapour deposition technology
- Excellent uniformity and reproducibility with fast turnaround cycle times
- BM platform: BM R&D (2-inch), BM Pro (4-inch and 6-inch), BM GB (4-inch glovebox), BM HT (high temperature, 1,700°C), BM300T (300mm)
- Graphene and carbon nanotube films for electronics, energy storage, thermal management, sensors and flexible/transparent applications

Product features

- Fast response heater and turnaround
- Thermal CVD
- Substrate and top heating
- Closed loop infrared wafer temperature control
- Plasma enhanced CVD with frequency control
- Flexible processing for different applications
- Low cost of ownership
- Easy maintenance and cleaning
- User management features and growth library

Graphene (2D) and Carbon nanotube (1D)
Unique combination of high electrical/thermal conductivity, mobility, flexibility and transparency

Serving R&D market today
AIXTRON BM Pro

Production ready for tomorrow
AIXTRON BM Pro 300
## Consolidated Income Statement*

<table>
<thead>
<tr>
<th>(€ million)</th>
<th>2015</th>
<th>2014</th>
<th>2013</th>
</tr>
</thead>
<tbody>
<tr>
<td>Revenues</td>
<td>197.8</td>
<td>193.8</td>
<td>182.9</td>
</tr>
<tr>
<td>Cost of sales</td>
<td>147.9</td>
<td>154.1**</td>
<td>204.7**</td>
</tr>
<tr>
<td>Gross profit</td>
<td>49.8</td>
<td>39.7**</td>
<td>-21.8**</td>
</tr>
<tr>
<td><strong>Gross Margin</strong></td>
<td><strong>25%</strong></td>
<td><strong>21%</strong></td>
<td><strong>-12%</strong></td>
</tr>
<tr>
<td>Selling expenses</td>
<td>11.5</td>
<td>14.1**</td>
<td>14.5**</td>
</tr>
<tr>
<td>General &amp; admin expenses</td>
<td>16.3</td>
<td>19.3</td>
<td>18.2</td>
</tr>
<tr>
<td>R&amp;D</td>
<td>55.4</td>
<td>66.7</td>
<td>57.2</td>
</tr>
<tr>
<td>Net other op.(income)/expenses</td>
<td>-6.7</td>
<td>-2.2</td>
<td>-16.0</td>
</tr>
<tr>
<td>EBITDA</td>
<td>-16.4</td>
<td>-41.3</td>
<td>-67.9</td>
</tr>
<tr>
<td>EBIT</td>
<td>-26.7</td>
<td>-58.3</td>
<td>-95.7</td>
</tr>
<tr>
<td><strong>EBIT Margin</strong></td>
<td><strong>-14%</strong></td>
<td><strong>-30%</strong></td>
<td><strong>-52%</strong></td>
</tr>
<tr>
<td>Result before tax</td>
<td>-26.0</td>
<td>-57.1</td>
<td>-95.2</td>
</tr>
<tr>
<td><strong>Pre-Tax Margin</strong></td>
<td><strong>-13%</strong></td>
<td><strong>-29%</strong></td>
<td><strong>-52%</strong></td>
</tr>
<tr>
<td>Net result</td>
<td>-29.2</td>
<td>-62.5</td>
<td>-101.0</td>
</tr>
<tr>
<td><strong>Net Return on Sales</strong></td>
<td><strong>-15%</strong></td>
<td><strong>-32%</strong></td>
<td><strong>-55%</strong></td>
</tr>
</tbody>
</table>

*) rounded figures; may not add up  
**) 2013 and 2014 figures changed to be comparable with 2015
# Consolidated Statement of Financial Position*

<table>
<thead>
<tr>
<th>(€ million)</th>
<th>31/12/15</th>
<th>31/12/14</th>
<th>31/12/13</th>
</tr>
</thead>
<tbody>
<tr>
<td>Property, plant &amp; equipment</td>
<td>81.3</td>
<td>77.3</td>
<td>79.9</td>
</tr>
<tr>
<td>Goodwill</td>
<td>75.9</td>
<td>64.8</td>
<td>64.1</td>
</tr>
<tr>
<td>Other intangible assets</td>
<td>6.4</td>
<td>2.5</td>
<td>3.1</td>
</tr>
<tr>
<td>Others</td>
<td>3.9</td>
<td>4.6</td>
<td>5.7</td>
</tr>
<tr>
<td><strong>Non-current assets</strong></td>
<td><strong>167.6</strong></td>
<td><strong>149.2</strong></td>
<td><strong>152.7</strong></td>
</tr>
<tr>
<td>Inventories, WIP &amp; Finished Goods</td>
<td>70.8</td>
<td>81.7</td>
<td>66.2</td>
</tr>
<tr>
<td>Trade receivables</td>
<td>26.0</td>
<td>26.3</td>
<td>27.7</td>
</tr>
<tr>
<td>Others</td>
<td>8.2</td>
<td>8.3</td>
<td>10.3</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalents incl. CD</td>
<td>209.4</td>
<td>268.1</td>
<td>306.3</td>
</tr>
<tr>
<td><strong>Current Assets</strong></td>
<td><strong>314.4</strong></td>
<td><strong>384.4</strong></td>
<td><strong>410.5</strong></td>
</tr>
<tr>
<td>Shareholders' equity</td>
<td><strong>396.5</strong></td>
<td><strong>415.7</strong></td>
<td><strong>465.4</strong></td>
</tr>
<tr>
<td><strong>Non-current liabilities</strong></td>
<td><strong>3.6</strong></td>
<td><strong>1.3</strong></td>
<td><strong>2.4</strong></td>
</tr>
<tr>
<td>Trade payables</td>
<td>9.8</td>
<td>16.4</td>
<td>13.5</td>
</tr>
<tr>
<td>Advance payments from customers</td>
<td>24.0</td>
<td>66.9</td>
<td>46.2</td>
</tr>
<tr>
<td>Others</td>
<td>48.0</td>
<td>33.2</td>
<td>35.7</td>
</tr>
<tr>
<td><strong>Current liabilities</strong></td>
<td><strong>81.8</strong></td>
<td><strong>116.5</strong></td>
<td><strong>95.4</strong></td>
</tr>
<tr>
<td><strong>Balance Sheet total</strong></td>
<td><strong>482.0</strong></td>
<td><strong>533.5</strong></td>
<td><strong>563.2</strong></td>
</tr>
</tbody>
</table>

*) rounded figures; may not add up
# Consolidated Statement of Cash Flows*

<table>
<thead>
<tr>
<th>(€ million)</th>
<th>2015</th>
<th>2014</th>
<th>2013</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash Flow from operating activities</td>
<td>-45.7</td>
<td>-33.8</td>
<td>8.2</td>
</tr>
<tr>
<td>Cash Flow from investing activities</td>
<td>41.2</td>
<td>-23.2</td>
<td>-39.7</td>
</tr>
<tr>
<td>Cash Flow from financing activities</td>
<td>-0.1</td>
<td>0.2</td>
<td>101.6</td>
</tr>
<tr>
<td>Exchange rate changes</td>
<td>4.3</td>
<td>5.9</td>
<td>-2.4</td>
</tr>
<tr>
<td>Net change in Cash &amp; Cash Equivalents</td>
<td>-0.3</td>
<td>-50.9</td>
<td>67.7</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalents (beginning of period)</td>
<td>116.6</td>
<td>167.5</td>
<td>99.7</td>
</tr>
<tr>
<td>Cash &amp; Cash Equivalents (end of period)</td>
<td>116.3</td>
<td>116.6</td>
<td>167.5</td>
</tr>
<tr>
<td>Change in Cash deposits</td>
<td>-60.5</td>
<td>9.9</td>
<td>30.4</td>
</tr>
<tr>
<td>Free Cash Flow**</td>
<td>-57.3</td>
<td>-47.0</td>
<td>-1.1</td>
</tr>
<tr>
<td>Capex</td>
<td>13.3</td>
<td>13.4</td>
<td>10.1</td>
</tr>
</tbody>
</table>

*) rounded figures; may not add up  
**) Operating CF + Investing CF + Changes in Cash Deposits, adjusted for acquisition effects
Annual Equipment Revenues by Application (excl. spares)

* Optoelectronics includes applications in Consumer Optoelectronics, Telecom/Datacom, Solar, etc.
Equipment Order Intake per Quarter

\( \text{EUR million} \)

- Driven by strategic China investments
- Overcapacity Absorption, Industry Consolidation
- Driven by LED TV
- Driven by notebook backlighting
- Driven by telecom/datacom and mobile phone penetration
- Driven by mobile phone penetration

- China Investments
- Compound Semiconductor Market
Global Presence

AIXTRON SE Headquarters
Herzogenrath, Germany

Core of AIXTRON’s activities is the Technology and R&D Center near Aachen.

Focus on engineering and process development in MOCVD and organic semiconductors.

AIXTRON Ltd.
Cambridge, United Kingdom

Focus on key MOCVD reactor component technology, carbon-based nanotechnology systems, state of the art innovation and production of R&D tools.

AIXTRON Inc.
Sunnyvale, California, USA

Focus on silicon applications for leading suppliers of DRAM and CMOS.
Financial Calendar & Contact Data

- May 25, 2016  Annual General Meeting, Aachen
- July 26, 2016  H1/2016 Results, Conference Call
- October 25, 2016  9M/2016 Results, Conference Call
- February 2017  FY/2016 Results, Conference Call

For further information please contact:

Investor Relations & Corporate Communications
AIXTRON SE  •  Dornkaulstr. 2  •  52134 Herzogenrath, Germany

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Thank you very much for your attention.